



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.5	
3	Layer 1 - Top Layer	Copper	1.70mil		
4	Dielectric1	370HR	4.05mil	4.2	
5	Layer 2 - GND	Copper	1.18mil		
6	Dielectric2	370HR	27.95mil	4.2	
7	Layer 3 - PWR	Copper	1.18mil		
8	Dielectric3	370HR	8.11mil	4.2	
9	Layer 4 - Signal	Copper	1.18mil		
10	Dielectric4	370HR	27.95mil	4.2	
11	Layer 5 - GND	Copper	1.18mil		
12	Dielectric5	370HR	4.05mil	4.2	
13	Layer 6 - Bottom Layer	Copper	1.70mil		
14	Bottom Solder	Solder Resist	0.50mi	3.5	DESIGN INFORMATION
15	Bottom Overlay				MIN. TRACK WIDTH: 0.1 mm

MIN. TRACK WIDTH:	<u>0.1</u> mm
MIN. CLEARANCE:	<u>0.13</u> mm
MIN. VIA PAD SIZE:	<u>0.5</u> mm
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- <u>3</u> MIL	

MATERIAL:

☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____

THICKNESS: ☐ 62 MIL (1.6mm) +/-10% ☒ OTHER 82 MIL

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

DRILLING: _____

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER _____

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____

SOLDER RESIST COLOR: ☒ GREEN ☐ OTHER _____

☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs
TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER



PROJECT TITLE:	ADAS Sensor Fusion Board
----------------	--------------------------

DESIGNED FOR:
Public Release

FILE NAME:
PCB1_test.PcbDoc

ENGINEER: Spectrum Digital	LAYOUT BY: Spectrum Digital
-------------------------------	--------------------------------

SCALE: 1.00	ALTUM DESIGNER VERSION: 17.0.11.656
-------------	--

Symbol	Count	Hole Size	Plated
▽	499	7.87mil (0.200mm)	PTH
✕	854	10.00mil (0.254mm)	PTH
⊕	73	15.00mil (0.381mm)	PTH
◇	6	24.00mil (0.610mm)	PTH
★	101	28.00mil (0.711mm)	PTH
⊗	16	35.43mil (0.900mm)	PTH
▽	81	40.00mil (1.016mm)	PTH
▣	2	40.16mil (1.020mm)	NPTH
◎	4	55.12mil (1.400mm)	PTH
☆	8	59.06mil (1.500mm)	PTH
○	22	63.00mil (1.600mm)	PTH
⊕	16	66.93mil (1.700mm)	PTH
✕	32	74.80mil (1.900mm)	PTH
□	4	125.98mil (3.200mm)	PTH
	1718 Total		

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: 518520C	REV: C	SUN REV: Not In VersionControl
LAYER NAME = 00059-2-10 Dimensions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 1/14/2019 7:31:52 AM		TEXAS INSTRUMENTS

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.